

VERSION SHOWING THE CHANGES TO THE ABSTRACT

Amend the abstract as follows:

~~Electronic component comprising predominantly organic functional materials and a process for the production thereof.~~

~~The invention concerns an electronic component comprising predominantly organic functional materials with improved through-plating. The through-plating is formed in the present case prior to application of the insulating layer, in the form of a free-standing raised portion.~~

An electronic component comprises a plurality of layers at least two of which comprise predominantly organic functional materials with improved through-plating through certain of the layers. The through-plating is formed in one embodiment by a disruption element on a first lower layer which results in a void in the subsequently applied layers, which void is filled with a material which may be conductive to form the through plating. In a second embodiment, the through plating is formed on the first lower layer prior to the subsequent application of the other layers, in the form of a free-standing truncated frusto-conical raised portion, and forms a disruption or non-wetting element for the subsequently applied other layers, formed on the first lower layer and which are engaged with and surround the through plating after their application.